



# BERGQUIST GAP FILLER TGF 1500

Known as BERGQUIST GAP FILLER 1500  
October 2018

## PRODUCT DESCRIPTION

A thermally conductive, liquid gap filler material.

|                                        |                                                         |
|----------------------------------------|---------------------------------------------------------|
| <b>Technology</b>                      | Silicone                                                |
| Appearance (cured)                     | Yellow                                                  |
| Appearance - Part A                    | Yellow                                                  |
| Appearance - Part B                    | White                                                   |
| <b>Cure</b>                            | Room temperature cure or Heat cure                      |
| <b>Application</b>                     | Thermal management,<br>TIM (Thermal Interface Material) |
| Mix Ratio by weight:<br>Part A: Part B | 1 : 1                                                   |
| Mix Ratio by volume:<br>Part A: Part B | 1 : 1                                                   |
| Solids Content, %                      | 100                                                     |
| Operating Temperature<br>Range         | -60 to 200°C                                            |

## FEATURES AND BENEFITS

- Thermal Conductivity: 1.8 W/m-K
- Optimized shear thinning characteristics for ease of dispensing
- Excellent slump resistance (stays in place)
- Ultra-conforming, with excellent wet-out for low stress interface applications
- 100% solids - no cure by-products
- Excellent low and high temperature mechanical and chemical stability

BERGQUIST GAP FILLER TGF 1500 is a two-part, high performance, thermally conductive liquid gap filling material, which features superior slump resistance and high shear thinning characteristics for optimized consistency and control during dispensing. The mixed system will cure at room temperature and can be accelerated with the addition of heat.

Unlike cured thermal pad materials, a liquid approach offers infinite thickness variations with little or no stress to the sensitive components during assembly. BERGQUIST GAP FILLER TGF 1500 exhibits low level natural tack characteristics and is intended for use in applications where a strong structural bond is not required.

As cured, BERGQUIST GAP FILLER TGF 1500 provides a soft, thermally conductive, form-in place elastomer that is ideal for fragile assemblies and filling unique and intricate air voids and gaps.

## TYPICAL APPLICATIONS

- Automotive electronics (HEV, NEV, batteries)
- Telecommunications
- Computer and peripherals
- Between any heat-generating semiconductor and a heat sink

## TYPICAL PROPERTIES OF UNCURED MATERIAL

Viscosity, High shear, Capillary, ASTM D5099, mPa·s (cP):  
3,000/ sec, Part A and B measured separately 25,000  
Density, ASTM D792, g/cc 2.7  
Pot Life @ 25°C, Parallel Plate Rheometer - Working life as liquid:  
@ 60 minutes  
@ 480 minutes  
Shelf Life @ 25°C, days 180

## TYPICAL CURE SCHEDULE

### Cure Schedule

5 hours @ 25°C  
10 minutes @ 100°C

### Alternate Cure Schedule

3 days @ 25°C  
30 minutes @ 100°C

Parallel plate rheometer, estimated time to reach 90% cure.

## TYPICAL PROPERTIES OF CURED MATERIAL

### Physical Properties

Hardness, Shore 00, Thirty second delay value, ASTM D2240 50  
Heat Capacity, ASTM D1269, J/g-K 1.0  
Flammability, UL 94 V-0

### Electrical Properties

Dielectric Strength, ASTM D149, V/mil 400  
Dielectric Constant, ASTM D150 @ 1,000 Hz 6.4  
Volume Resistivity, ASTM D257, ohm-meter  $1 \times 10^{10}$

### Thermal Properties

Thermal Conductivity, ASTM D5470, W/(m-K) 1.8

## GENERAL INFORMATION

For safe handling information on this product, consult the Safety Data Sheet, (SDS).



**Not for product specifications**

The technical data contained herein are intended as reference only. Please contact your local quality department for assistance and recommendations on specifications for this product.

The above cure profiles are guideline recommendations. Cure conditions (time and temperature) may vary based on customers' experience and their application requirements, as well as customer curing equipment, oven loading and actual oven temperatures.

**CONFIGURATIONS AVAILABLE**

BERGQUIST GAP FILLER TGF 1500 is available in the following configurations:

- Cartridges
- Kits
- With or without glass beads

**STORAGE**

Store product in the unopened container in a dry location. Storage information may be indicated on the product container labeling.

Optimal Storage: 5 to 25°C for a 6 month shelf life. Material removed from containers may be contaminated during use. Do not return product to the original container. Henkel Corporation cannot assume responsibility for product which has been contaminated or stored under conditions other than those previously indicated. If additional information is required, please contact your local Technical Service Center or Customer Service Representative.

**Conversions**

$(^{\circ}\text{C} \times 1.8) + 32 = ^{\circ}\text{F}$   
 $\text{kV/mm} \times 25.4 = \text{V/mil}$   
 $\text{mm} / 25.4 = \text{inches}$   
 $\text{N} \times 0.225 = \text{lb}$   
 $\text{N/mm} \times 5.71 = \text{lb/in}$   
 $\text{psi} \times 145 = \text{N/mm}^2$   
 $\text{MPa} = \text{N/mm}^2$   
 $\text{N}\cdot\text{m} \times 8.851 = \text{lb}\cdot\text{in}$   
 $\text{N}\cdot\text{m} \times 0.738 = \text{lb}\cdot\text{ft}$   
 $\text{N}\cdot\text{mm} \times 0.142 = \text{oz}\cdot\text{in}$   
 $\text{mPa}\cdot\text{s} = \text{cP}$

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**Reference 1**

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Нашей специализацией является поставка электронной компонентной базы двойного назначения, продукции таких производителей как XILINX, Intel (ex.ALTERA), Vicor, Microchip, Texas Instruments, Analog Devices, Mini-Circuits, Amphenol, Glenair.

Сотрудничество с глобальными дистрибьюторами электронных компонентов, предоставляет возможность заказывать и получать с международных складов практически любой перечень компонентов в оптимальные для Вас сроки.

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Система менеджмента качества компании отвечает требованиям в соответствии с ГОСТ Р ИСО 9001, ГОСТ РВ 0015-002 и ЭС РД 009

### Офис по работе с юридическими лицами:

105318, г.Москва, ул.Щербаковская д.3, офис 1107, 1118, ДЦ «Щербаковский»

Телефон: +7 495 668-12-70 (многоканальный)

Факс: +7 495 668-12-70 (доб.304)

E-mail: [info@moschip.ru](mailto:info@moschip.ru)

Skype отдела продаж:

moschip.ru

moschip.ru\_4

moschip.ru\_6

moschip.ru\_9